

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: <b>Sun, et al.</b>	§	Case: <b>AMAT/8241/CMP/ECP/RKK</b>
	§	
Serial No.: <b>10/616,097</b>	§	Filed: <b>July 8, 2003</b>
	§	
Examiner: <b>Edna Wong</b>	§	Group Art Unit: <b>1753</b>
	§	
Confirmation No.: <b>1645</b>	§	
	§	
Title: <b>MULTIPLE-STEP</b>	§	
<b>ELECTRODEPOSITION PROCESS</b>	§	
<b>FOR DIRECT COPPER PLATING ON</b>	§	
<b>BARRIER MATERIALS</b>	§	

MAIL STOP Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**RESPONSE TO OFFICE ACTION DATED JULY 13, 2007**

In response to the Office Action dated July 13, 2007 having a shortened statutory period for response set to expire on October 13, 2007, please enter this response and reconsider the claims pending in the application for the reasons discussed below. Applicants believe that a one-month extension fee is due in connection with this response. This fee has been paid with the submission of this paper using the Patent Electronic Business Center. The Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782 for any other fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.